Low-Voltage 1.8/2.5/3.3 V 8-Bit Transceiver

(3-State, Non-Inverting with Bushold)

The 74VCXH245 is an advanced performance, non-inverting 8-bit transceiver. It is designed for very high-speed, very low-power operation in 1.8 V, 2.5 V or 3.3 V systems.

The 74VCXH245 is designed as a byte control. The Transmit/Receive ($T/\overline{R}n$) inputs determine the direction of data flow through the bidirectional transceiver. Transmit (active–HIGH) enables data from A ports to B ports; Receive (active–LOW) enables data from B to A ports. The Output Enable input (\overline{OE}), when HIGH, disables both A and B ports by placing them in a HIGH Z condition. The data inputs include active bushold circuitry, eliminating the need for external pullup resistors to hold unused or floating inputs at a valid logic state.

Features

• Designed for Low Voltage Operation: $V_{CC} = 1.65-3.6 \text{ V}$

• High Speed Operation: 3.5 ns max for 3.0 to 3.6 V

4.2 ns max for 2.3 to 2.7 V 8.4 ns max for 1.65 to 1.95 V

• Static Drive: ±24 mA Drive at 3.0 V

±18 mA Drive at 2.3 V ±6 mA Drive at 1.65 V

- Includes Active Bushold to Hold Unused or Floating Data Inputs at a Valid Logic State
- Near Zero Static Supply Current in All Three Logic States (20 μA) Substantially Reduces System Power Requirements
- Latchup Performance Exceeds ±200 mA @ 85°C
- ESD Performance:

Human Body Model >2000 V Machine Model >200 V

• Pb-Free Package is Available

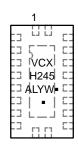


http://onsemi.com

MARKING DIAGRAM



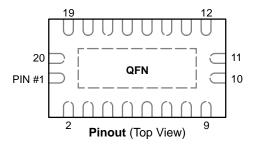
QFN MNR2 SUFFIX CASE 485AA



A = Assembly Location

L = Wafer Lot Y = Year W = Work Week ■ Pb-Free Package

(Note: Microdot may be in either location)



ORDERING INFORMATION

Device	Package	Shipping [†]
74VCXH245MNR2	QFN	3000/Tape&Reel
74VCXH245MNR2G	QFN (Pb-Free)	3000/Tape&Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

^{*}For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PIN NAMES

PINS	FUNCTION
OE	Output Enable Input
T/R	Transmit/Receive Input
A0–A7	Side A Bushold Inputs or 3–State Outputs
B0–B7	Side B Bushold Inputs or 3–State Outputs

TRUTH TABLE

INP	UTS	OPERATING MODE
ŌĒ	T/R	Non-Inverting
L	L	B Data to A Bus
L	Н	A Data to B Bus
Н	Х	Z State

H = High Voltage Level L = Low Voltage Level

Z = High Impedance State

X = High or Low Voltage Level and Transitions are Acceptable

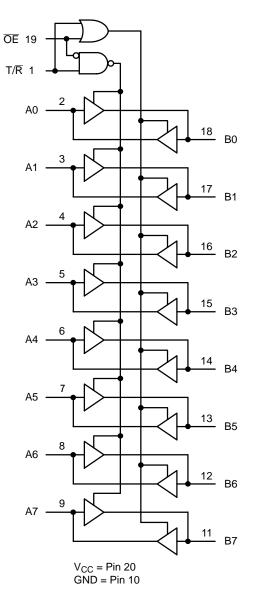


Figure 1. Logic Diagram

ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Value	Condition	Unit
V _{CC}	DC Supply Voltage	-0.5 to + 4.6		V
VI	DC Input Voltage	$-0.5 \le V_{I} \le V_{CC} + 0.5$		V
Vo	DC Output Voltage	$-0.5 \le V_{O} \le V_{CC} + 0.5$	Note 1	V
I _{IK}	DC Input Diode Current	-50	V _I < GND	mA
I _{OK}	DC Output Diode Current	-50	V _O < GND	mA
		+50	V _O > V _{CC}	mA
Ιο	DC Output Source/Sink Current	±50		mA
I _{CC}	DC Supply Current Per Supply Pin	±100		mA
I _{GND}	DC Ground Current Per Ground Pin	±100		mA
T _{STG}	Storage Temperature Range	-65 to +150		°C

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

1. I_O absolute maximum rating must be observed.

RECOMMENDED OPERATING CONDITIONS (Note 2)

Symbol	Parameter		Тур	Max	Unit
V _{CC}	Supply Voltage Operating Data Retention Only	1.65 1.2	3.3 3.3	3.6 3.6	V
VI	Input Voltage	-0.3		V _{CC}	V
Vo	Output Voltage	0		V _{CC}	V
I _{OH}	HIGH Level Output Current, V _{CC} = 3.0 V – 3.6 V			-24	mA
l _{OL}	LOW Level Output Current, V _{CC} = 3.0 V – 3.6 V			24	mA
I _{OH}	HIGH Level Output Current, V _{CC} = 2.3 V – 2.7 V			-18	mA
l _{OL}	LOW Level Output Current, V _{CC} = 2.3 V - 2.7 V			18	mA
I _{OH}	HIGH Level Output Current, V _{CC} = 1.65 V - 1.95 V			-6	mA
l _{OL}	LOW Level Output Current, V _{CC} = 1.65 V – 1.95 V			6	mA
T _A	Operating Free–Air Temperature			+85	°C
Δt/ΔV	Input Transition Rise or Fall Rate, V_{IN} from 0.8 V to 2.0 V, V_{CC} = 3.0 V	0		10	ns/V

^{2.} Floating or unused control inputs must be held HIGH or LOW.

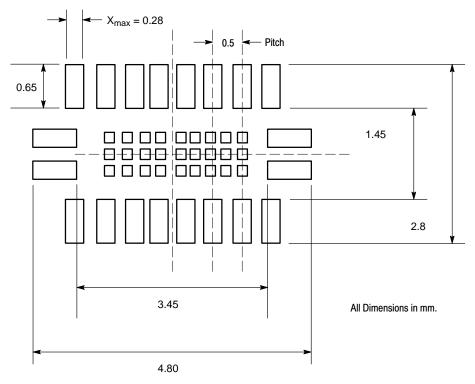


Figure 2. 20 Pad QFN Suggested Board Layout (Bottom View)

DC ELECTRICAL CHARACTERISTICS

			T _A = -40°	$T_A = -40^{\circ}C \text{ to } +85^{\circ}C$	
Symbol	Characteristic	Condition	Min	Max	Unit
V _{IH}	HIGH Level Input Voltage (Note 3)	1.65 V ≤ V _{CC} < 1.95 V	0.65 x V _{CC}		V
		2.3 V ≤ V _{CC} ≤ 2.7 V	1.6		
		2.7 V < V _{CC} ≤ 3.6 V	2.0		
V _{IL}	LOW Level Input Voltage (Note 3)	1.65 V ≤ V _{CC} < 1.95 V		0.35 x V _{CC}	V
		2.3 V ≤ V _{CC} ≤ 2.7 V		0.7	
		2.7 V < V _{CC} ≤ 3.6 V		0.8	
V _{OH}	HIGH Level Output Voltage	$1.65 \text{ V} \le \text{V}_{CC} \le 3.6 \text{ V}; \text{ I}_{OH} = -100 \mu\text{A}$	V _{CC} - 0.2		V
		$V_{CC} = 1.65 \text{ V}; I_{OH} = -6 \text{ mA}$	1.25		
		$V_{CC} = 2.3 \text{ V}; I_{OH} = -6 \text{ mA}$	2.0		
		$V_{CC} = 2.3 \text{ V; } I_{OH} = -12 \text{ mA}$	1.8		
		$V_{CC} = 2.3 \text{ V; } I_{OH} = -18 \text{ mA}$	1.7		
		$V_{CC} = 2.7 \text{ V; } I_{OH} = -12 \text{ mA}$	2.2		
		$V_{CC} = 3.0 \text{ V; } I_{OH} = -18 \text{ mA}$	2.4		
		$V_{CC} = 3.0 \text{ V; } I_{OH} = -24 \text{ mA}$	2.2		
V _{OL}	LOW Level Output Voltage	$1.65 \text{ V} \le \text{V}_{CC} \le 3.6 \text{ V}; \text{ I}_{OL} = 100 \mu\text{A}$		0.2	V
		V _{CC} = 1.65 V; I _{OL} = 6 mA		0.3	
		V _{CC} = 2.3 V; I _{OL} = 12 mA		0.4	
		V _{CC} = 2.3 V; I _{OL} = 18 mA		0.6	
		V _{CC} = 2.7 V; I _{OL} = 12 mA		0.4	
		V _{CC} = 3.0 V; I _{OL} = 18 mA		0.4	
		V _{CC} = 3.0 V; I _{OL} = 24 mA		0.55	
I _I	Input Leakage Current	$V_{IN} = V_{CC}$ or GND; $V_{CC} = 3.6 \text{ V}$		±5.0	μΑ
I _{I(HOLD)}	Minimum Bushold Input Current	$V_{CC} = 3.0 \text{ V}, V_{IN} = 0.8 \text{ V}$	75		μΑ
		$V_{CC} = 3.0 \text{ V}, V_{IN} = 2.0 \text{ V}$	-75		
		$V_{CC} = 2.3 \text{ V}, V_{IN} = 0.7 \text{ V}$	45		
		$V_{CC} = 2.3 \text{ V}, V_{IN} = 1.6 \text{ V}$	-45		
		V _{CC} = 1.65 V, V _{IN} = 0.57 V	25		
		V _{CC} = 1.65 V, V _{IN} = 1.07 V	-25		
I _{I(OD)}	Minimum Bushold Over-Drive	V _{CC} = 3.6 V, (Note 4)	450		μΑ
	Current Needed to Change State	V _{CC} = 3.6 V, (Note 5)	-450		
		V _{CC} = 2.7 V, (Note 4)	300		
		V _{CC} = 2.7 V, (Note 5)	-300		
		V _{CC} = 1.95 V, (Note 4)	200		
		V _{CC} = 1.95 V, (Note 5)	-200		
l _{OZ}	3-State Output Current	$V_O = V_{CC}$ or GND; $V_{CC} = 3.6$ V; $V_I = V_{IH}$ or V_{IL}		±10	μΑ
I _{CC}	Quiescent Supply Current (Note 6)	1.65 V \leq V _{CC} \leq 3.6 V; V _I = GND or V _{CC}		20	μΑ
ΔI_{CC}	Increase in I _{CC} per Input	$2.7 \text{ V} < \text{V}_{CC} \le 3.6 \text{ V}; \text{V}_{IH} = \text{V}_{CC} - 0.6 \text{ V}$		750	μΑ

These values of V_I are used to test DC electrical characteristics only.
 An external driver must source at least the specified current to switch from LOW-to-HIGH.
 An external driver must sink at least the specified current to switch from HIGH-to-LOW.
 Outputs disabled or 3-state only.

AC CHARACTERISTICS (Note 7; $t_R = t_F = 2.0 \text{ ns}$; $C_L = 30 \text{ pF}$; $R_L = 500 \Omega$)

					Li	mits			
					$T_A = -40^{\circ}$	°C to +85°C	;		
			V _{CC} = 3.0	V to 3.6 V	V _{CC} = 2.3	V to 2.7 V	V _{CC} = 1.65	V to1.95 V	
Symbol	Parameter	Waveform	Min	Max	Min	Max	Min	Max	Unit
t _{PLH} t _{PHL}	Propagation Delay Input to Output	1	0.6 0.6	3.5 3.5	0.8 0.8	4.2 4.2	1.5 1.5	8.4 8.4	ns
t _{PZH} t _{PZL}	Output Enable Time to High and Low Level	2	0.6 0.6	4.5 4.5	0.8 0.8	5.6 5.6	1.5 1.5	9.8 9.8	ns
t _{PHZ} t _{PLZ}	Output Disable Time From High and Low Level	2	0.6 0.6	3.6 3.6	0.8 0.8	4.0 4.0	1.5 1.5	7.2 7.2	ns
t _{OSHL} t _{OSLH}	Output-to-Output Skew (Note 8)			0.5 0.5		0.5 0.5		0.75 0.75	ns

^{7.} For $C_L = 50$ pF, add approximately 300 ps to the AC maximum specification.

DYNAMIC SWITCHING CHARACTERISTICS

			T _A = +25°C	
Symbol	Characteristic	Condition	Тур	Unit
V _{OLP}	Dynamic LOW Peak Voltage	$V_{CC} = 1.8 \text{ V}, \ C_L = 30 \text{ pF}, \ V_{IH} = V_{CC}, \ V_{IL} = 0 \text{ V}$	0.3	V
	(Note 9)	$V_{CC} = 2.5 \text{ V}, C_L = 30 \text{ pF}, V_{IH} = V_{CC}, V_{IL} = 0 \text{ V}$	0.7	
		V_{CC} = 3.3 V, C_L = 30 pF, V_{IH} = V_{CC} , V_{IL} = 0 V	1.0	
V _{OLV}	Dynamic LOW Valley Voltage	$V_{CC} = 1.8 \text{ V}, C_L = 30 \text{ pF}, V_{IH} = V_{CC}, V_{IL} = 0 \text{ V}$	-0.3	V
	(Note 9)	$V_{CC} = 2.5 \text{ V}, C_L = 30 \text{ pF}, V_{IH} = V_{CC}, V_{IL} = 0 \text{ V}$	-0.7	
		V_{CC} = 3.3 V, C_L = 30 pF, V_{IH} = V_{CC} , V_{IL} = 0 V	-1.0	
V _{OHV}	Dynamic HIGH Valley Voltage	$V_{CC} = 1.8 \text{ V}, C_L = 30 \text{ pF}, V_{IH} = V_{CC}, V_{IL} = 0 \text{ V}$	1.3	V
	(Note 10)	V_{CC} = 2.5 V, C_L = 30 pF, V_{IH} = V_{CC} , V_{IL} = 0 V	1.7	
		$V_{CC} = 3.3 \text{ V}, C_L = 30 \text{ pF}, V_{IH} = V_{CC}, V_{IL} = 0 \text{ V}$	2.0	7

^{9.} Number of outputs defined as "n". Measured with "n-1" outputs switching from HIGH-to-LOW or LOW-to-HIGH. The remaining output is measured in the LOW state.

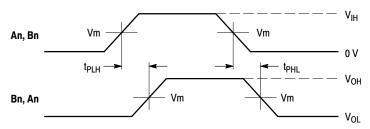
CAPACITIVE CHARACTERISTICS

Symbol	Parameter	Condition	Typical	Unit
C _{IN}	Input Capacitance	Note 11	6	pF
C _{OUT}	Output Capacitance	Note 11	7	pF
C _{PD}	Power Dissipation Capacitance	Note 11, 10 MHz	20	pF

^{11.} $V_{CC} = 1.8$, 2.5 or 3.3 V; $V_I = 0$ V or V_{CC} .

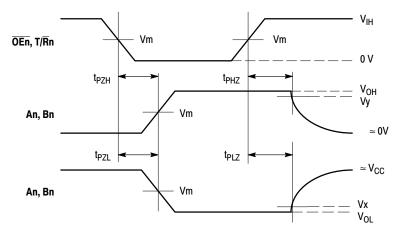
Skew is defined as the absolute value of the difference between the actual propagation delay for any two separate outputs of the same device.
 The specification applies to any outputs switching in the same direction, either HIGH-to-LOW (t_{OSHL}) or LOW-to-HIGH (t_{OSLH}); parameter guaranteed by design.

^{10.} Number of outputs defined as "n". Measured with "n-1" outputs switching from HIGH-to-LOW or LOW-to-HIGH. The remaining output is measured in the HIGH state.



WAVEFORM 1 - PROPAGATION DELAYS

 t_R = t_F = 2.0 ns, 10% to 90%; f = 1 MHz; t_W = 500 ns

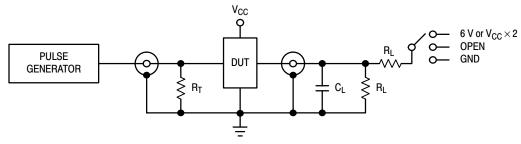


WAVEFORM 2 - OUTPUT ENABLE AND DISABLE TIMES

 $t_R = t_F = 2.0 \text{ ns}, 10\% \text{ to } 90\%; f = 1 \text{ MHz}; t_W = 500 \text{ ns}$

Figure 3. AC Waveforms

	V _{CC}		
Symbol	3.3 V \pm 0.3 V	2.5 V \pm 0.2 V	1.8 V \pm 0.15 V
V _{IH}	2.7 V	V _{CC}	V _{CC}
V _m	1.5 V	V _{CC} /2	V _{CC} /2
V _x	V _{OL} + 0.3 V	V _{OL} + 0.15 V	V _{OL} + 0.15 V
V _y	V _{OH} – 0.3 V	V _{OH} – 0.15 V	V _{OH} – 0.15 V



TEST	SWITCH
t _{PLH} , t _{PHL}	Open
t _{PZL} , t _{PLZ}	6 V at V_{CC} = 3.3 ± 0.3 V; V_{CC} × 2 at V_{CC} = 2.5 ± 0.2 V; 1.8 V ± 0.15 V
t _{PZH} , t _{PHZ}	GND

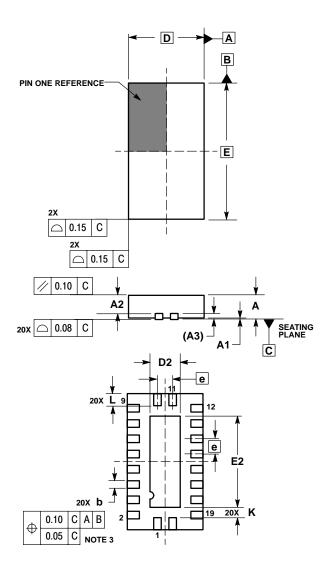
 $C_L = 30 \text{ pF}$ or equivalent (Includes jig and probe capacitance)

 $R_L = 500 \ \Omega$ or equivalent $R_T = Z_{OUT}$ of pulse generator (typically 50 Ω)

Figure 4. Test Circuit

PACKAGE DIMENSIONS

QFN **MNR2 SUFFIX** CASE 485AA-01 ISSUE A



- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: MILLIMETERS.
 3. DIMENSIONS & APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.25 AND 0.30 MM FROM TERMINAL.
 4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

	MILLIMETERS			
DIM	MIN	MAX		
Α	0.80	1.00		
A1	0.00	0.05		
A2	0.65	0.75		
A3	0.20	REF		
b	0.20	0.30		
D	2.50	BSC		
D2	0.85	1.15		
Е	4.50	BSC		
E2	2.85	3.15		
е	0.50 BSC			
K	0.20			
L	0.35	0.45		

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